

**SINGLE-PHASE GLASS PASSIVATED
SILICON BRIDGE RECTIFIER**
Reverse Voltage – 50 to 1000 Volts
Forward Current – 1.0 Ampere

Features

- Glass passivated chip junction
- Low forward voltage drop
- High surge overload rating of 50 Amperes peak
- Ideal for printed circuit board
- High temperature soldering guaranteed:
260°C for 10 seconds

Mechanical Data

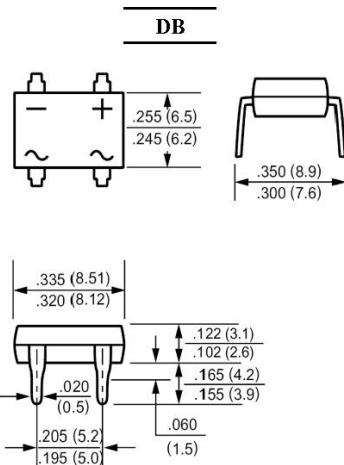
Case: Molded plastic, DB

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202,
method 208 guaranteed

Mounting position: Any

Weight: 0.02ounce, 0.4gram



Dimensions in inches and (millimeters)

Absolute Maximum Ratings and Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

	Symbols	DF005	DF01	DF02	DF04	DF06	DF08	DF10	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T _A = 40 °C	I _(AV)					1			A
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I _{FSM}					50			A
Maximum Forward Voltage at 1A DC	V _F				1.1				V
Maximum Reverse Voltage at Rated DC Blocking Voltage	I _R				5				µA
at T _A = 25°C					500				
Typical Junction Capacitance ¹⁾	C _J			25					pF
Typical Thermal Resistance ²⁾	R _{θJA}			40					°C/W
Typical Thermal Resistance ²⁾	R _{θJL}			15					°C/W
Operating and storage temperature range	T _J , T _S			-55 to +150					°C

¹⁾ Measured at 1MHz and applied reverse voltage of 4VDC.

²⁾ Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.5 x 0.5" (13 x 13mm) copper pads.

RATINGS AND CHARACTERISTIC CURVES

